



Notes: (Unless Otherwise Specified).

1. DIE MATERIAL IS SILICON.
2. METALLIZATION 1.0  $\mu$ m ALUMINUM (Al).
3. DIE IS WITHOUT PASSIVATION.
4. WIRE BONDABLE WITH GOLD (Au) OR ALUMINUM (Al) WIRE.
5. ISOLATED PADS 100 $\mu$ m SQUARE (48 PLACES).

DIMENSIONS IN MICRONS  
1000  $\mu$ m = 1.0 mm

PART NUMBER SYSTEM						
TD	-	48	-	4.1	-	ISO
SILICON		BOND		DIE SIZE		ISOLATED
TEST DIE		PADS		(mm)		PADS

APPROVALS		DATE	<b>TopLine</b> <sup>®</sup>			
DRAWN	T. Au	04/27/13				
ENG	M. Hart	04/27/13	TITLE Si TEST DIE TD48 4.1x4.1MM (100 $\mu$ m SQ Pads)			
MFG						
QA			SCALE	SIZE	DRAWING NO.	REV
CUST				A	154148	A
REVISED			DO NOT SCALE DRAWING			SHEET 1 OF 1